

AMENDMENTS TO THE CLAIMS

The following is a complete, marked-up listing of revised claims with a status identifier in parenthesis, underlined text indicating insertions, and strike through and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (Currently Amended) A polishing pad which performs a polishing operation by moving in contact with a surface of an object being polished, the polishing pad comprising:

a polishing layer composed of a hydrophilic polymeric matrix and liquid non-water soluble microelements embedded in the polymeric matrix,

wherein open pores defined by the embedded liquid microelements are distributed across a surface of the polishing layer, and

wherein the liquid material of the polishing pad includes at least one material selected from the group consisting of aliphatic mineral oil, aromatic mineral oil, silicon oil without a hydroxyl group in a molecule, soybean oil, coconut oil, palm oil, cotton seed oil, camellia oil, and hardened oil.

2. (Cancelled)

3. (Previously Presented) The polishing pad of claim 1, wherein the hydrophilic polymeric matrix is formed by introducing a hydrophilic compound into a material for the polymeric matrix through chemical bonding or mixing.

4. (Original) The polishing pad of claim 3, wherein the hydrophilic polymeric matrix contains 1-20 weight percent of the hydrophilic compound, based on the total weight of an isocyanate prepolymer.

5. (Previously Presented) The polishing pad of claim 3, wherein the hydrophilic compound comprises at least one material selected from the group consisting of polyethylene glycol, polyethylenepropylene glycol, polyoxyethylene alkylphenoether, polyoxyethylene alkylether, polyethylene glycol fatty acid ester, polyoxyethylene alkylamine ether, glycerine fatty acid ester, sugar fatty acid ester, and sorbitol fatty acid ester.

6. (Original) The polishing pad of claim 5, wherein the hydrophilic compound is polyethylene glycol having a molecular weight of 200-10000.

7. (Previously Presented) The polishing pad of claim 1, further comprising a support layer, which has a seamless interface with the polishing layer and is transparent or semitransparent to light used to detect the state of the surface of the object being polished.

8. (Original) The polishing pad of claim 1, wherein the polishing layer further comprises hollow polymeric microelements embedded in the polymeric matrix, and open pores defined by the hollow polymeric microelements are also distributed across the surface of the polishing layer.

9. (Original) The polishing pad of claim 1, wherein when the surface of the polishing layer is abraded by the polishing operation, the embedded liquid microelements are exposed at the surface of the polishing layer so that the open pores are continuously formed.

10. (Original) The polishing pad of claim 1, wherein the embedded liquid microelements are spherical microelements uniformly distributed within the polymeric matrix.

11. (Original) The polishing pad of claim 10, wherein an average diameter of the embedded liquid microelements and the pores is in a range of 1-60 μm .

12. (Original) The polishing pad of claim 1, wherein a material for the embedded liquid microelements is a liquid material which is chemically incompatible with the polymeric matrix.

13. (Cancelled).

14. (Original) The polishing pad of claim 12, wherein the content of the liquid material is 20-50 weight percent, based on the total weight of a material for the polymeric matrix.

15. (Original) The polishing pad of claim 1, further comprising a structure or pattern including a flow channel on the surface of the polishing layer in order to facilitate delivery of a polishing slurry.

16. (Original) The polishing pad of claim 1, wherein the polishing layer is semitransparent to light used to detect the state of the surface of the object being polished.

17-31. (Cancelled).